

IN THE SPECIFICATION

Please replace the following paragraph beginning at page 14, line 13 and ending at page 14, line 22 with the following rewritten paragraph:

-- Thereafter, with the wafer holder 51 being rotated in its wafer-holding plane, a fluid in the form of slurry, in which a plurality of semiconductor laser chips 11 have been dispersed, is poured over the principal surface of the wafer 10A that is held on the upper face of the wafer holder 51 in a slanting position. In this manner, the first semiconductor laser chips 11 are settled into the respective first openings 30a formed in the template 30B. Since the fluid in the form of slurry is circulated by the pump 60, the first semiconductor laser chips [[chip]] 11 which are not disposed into the first openings 30a can be collected and reused any number of times. In this embodiment, since the wafer 10A held in the fluid is rotated in its principal surface, the first semiconductor laser chips 11 can be effectively engaged into the first openings 30a in the template 30B.--